DATA SHEET



# SILICON POWER TRANSISTOR 2SA1649, 2SA1649-Z

PNP SILICON EPITAXIAL POWER TRANSISTOR FOR HIGH-SPEED SWITCHING

The 2SA1649 is a mold power transistor developed for highspeed switching and features a very low collector-to-emitter saturation voltage.

This transistor is ideal for use in switching regulators, DC/DC converters, motor drivers, solenoid drivers, and other low-voltage power supply devices, as well as for high-current switching.

#### FEATURES

- · Available for high-current control in small dimension
- Z type is a lead processed product and is deal for mounting a hybrid IC.
- Mold package that does not require an insulating board or insulation bushing
- Low collector saturation voltage: V<sub>CE(sat)</sub> = -0.3 V MAX. (@Ic = -3 A)
- Fast switching speed:
   tf = 0.3 μs MAX. (@Ic = -3 A)
- · High DC current amplifiers and excellent linearity

# ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	Vсво	-40	V
Collector to emitter voltage	Vceo	-30	V
Emitter to base voltage	Vebo	-7.0	V
Collector current (DC)	IC(DC)	-10	А
Collector current (pulse)	C(pulse)*	-20	А
Base current (DC)	IB(DC)	-3.5	А
Total power dissipation	P⊤ (Tc = 25 °C)	15	W
Total power dissipation	P⊤ (Ta = 25 °C)	1.0**, 2.0***	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

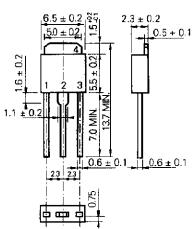
- \*: PW  $\leq$  300  $\mu$ s, duty cycle  $\leq$  10%
- \*\*: Printing board mounted

\*\*\*: 7.5  $\text{mm}^2 \times 0.7$  mm ceramic board mounted

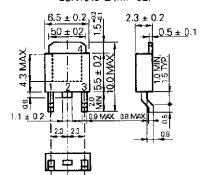
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# PACKAGE DRAWING (UNIT: mm)

#### 2SA1649 (MP-3)



2SA1649-Z (MP-3Z)



Electrode Connection

1. Base 2. Collector

3. Emitter

4. Fin (collector)

# ELECTRICA64 CHARACTERISTICS (Ta = 25°C)

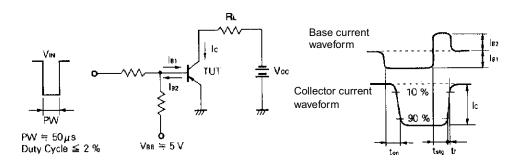
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Collector to emitter voltage	VCEO(SUS)	Ic = -4.0 A, I <sub>B</sub> = -0.4 A, L = 1 mH	-30			V
Collector to emitter voltage	VCEX(SUS)	Ic = -4.0 A, I <sub>B2</sub> = -I <sub>B1</sub> = -0.4 A, V <sub>BE(OFF)</sub> = 1.5 V, L = 180 $\mu$ H, clamped	-40			V
Collector cutoff current	Ісво	$V_{CE} = -30 \text{ V}, \text{ IE} = 0$			-10	μA
Collector cutoff current	ICER	$V_{CE} = -30 \text{ V}, \text{ R}_{BE} = 50 \Omega, \text{ Ta} = 125^{\circ}\text{C}$			-1.0	mA
Collector cutoff current	ICEX1	Vce = -30 V, VBE(OFF) = 1.5 V			-10	μA
Collector cutoff current	ICEX2	$V_{CE} = -30 \text{ V}, \text{ V}_{BE(OFF)} = 1.5 \text{ V},$ Ta = 125°C			-1.0	mA
Emitter cutoff current	Іево	V <sub>EB</sub> = -5.0 V, Ic = 0			-10	μA
DC current gain	hfe1*	Vce = -2.0 V, Ic = -0.5 A	100			-
DC current gain	hfe2*	Vce = -2.0 V, Ic = -2.0 A	100	200	400	-
DC current gain	hfe3*	Vce = -2.0 V, Ic = -4.0 A	60			-
Collector saturation voltage	V <sub>CE(sat)1</sub> *	Ic = −3.0 A, I <sub>B</sub> = −0.2 A			-0.3	V
Collector saturation voltage	VCE(sat)2*	Ic = -4.0 A, I <sub>B</sub> = -0.3 A			-0.5	V
Base saturation voltage	VBE(sat)1*	Ic = −3.0 A, I <sub>B</sub> = −0.2 A			-1.2	V
Base saturation voltage	VBE(sat)2*	Ic = −4.0 A, I <sub>B</sub> = −0.3 A			-1.5	V
Collector capacitance	Cob	$V_{CB} = -10 V$ , $I_E = 0$ , $f = 1.0 MHz$		250		pF
Gain bandwidth product	f⊤	$V_{CE} = -10 \text{ V}, \text{ Ic} = -0.5 \text{ A}$		120		MHz
Turn-on time	ton	Ic = $-4.0$ A, R <sub>L</sub> = 5 Ω,			0.3	μs
Storage time	tstg	$I_{B1} = -I_{B2} = -0.15 \text{ A}, \text{ Vcc} \cong -20 \text{ V}$ Refer to the test circuit.			1.5	μs
Fall time	tr				0.3	μs

\* Pulse test PW  $\leq$  350  $\mu$ s, duty cycle  $\leq$  2%/pulsed

# **hfe CLASSIFICATION**

Marking	М	L	к
hfe2	100 to 200	150 to 300	200 to 400

SWITCHING TIME (ton, tstg, tf) TEST CIRCUIT



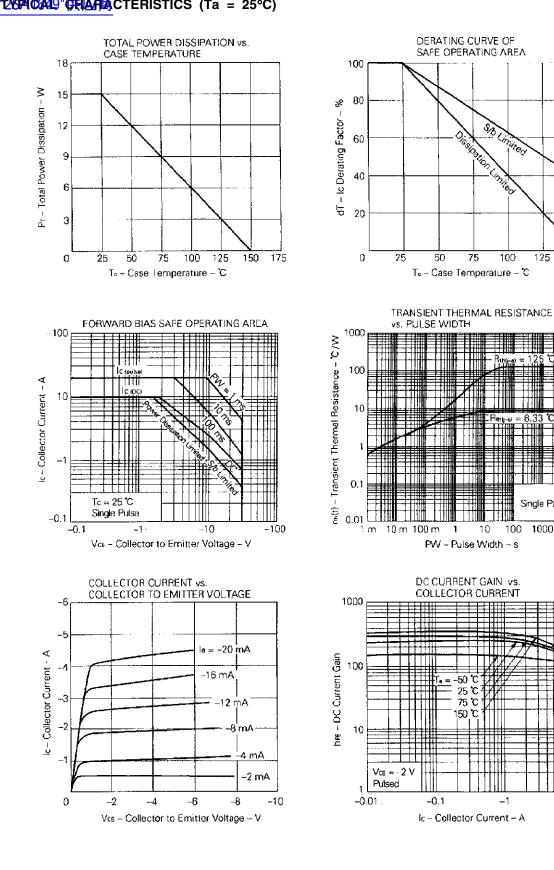
150

125

Single Pulse

1000 10000

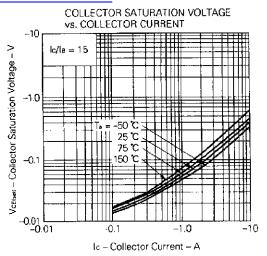
-10

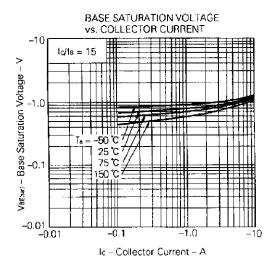


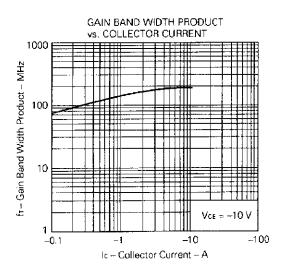
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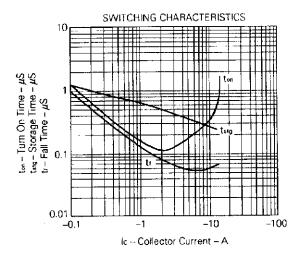
# 查询"2SA1649"供应商

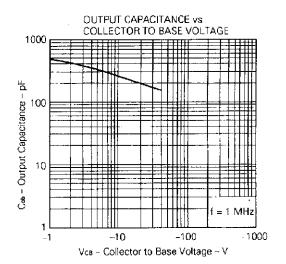
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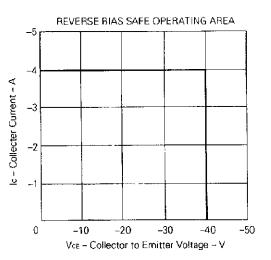












查询[[MEM049"供应商

# 查询"2SA1649"供应商

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